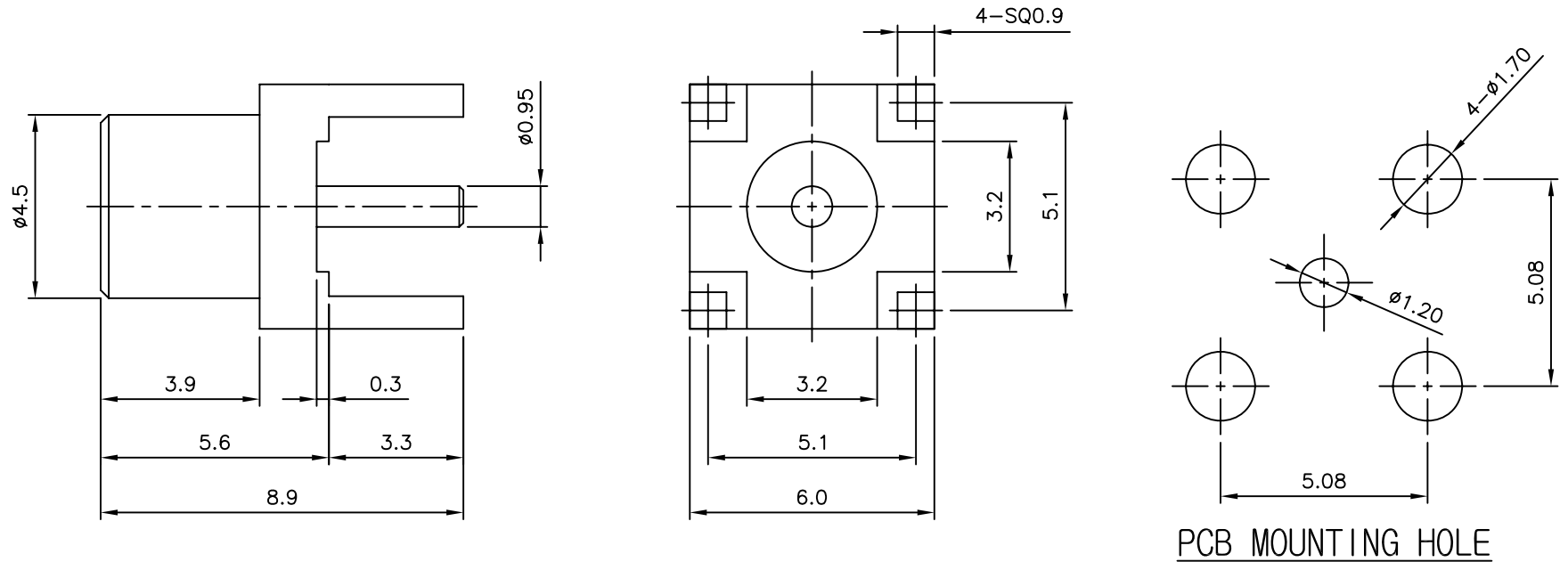


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	E.H.KIM	I.C.KIM	2014.10.17.
1	[설면처리No.201503-0006] (가시미 조립 후 절연체 밀림 현상 개선 형상 변경)	H.J.LEE	I.C.KIM	2015.03.25.
2	[설면처리No.202105-0015] BENDING -> HOOK 구조 변경	S.Y.EUN	I.C.KIM	2021.05.27.



2	1	3	INSULATOR	1	TEFLON		DIN00030-N/2 DIN01115-N/1
		2	CONTACT	1	BeCu	Gold Plate	DCT01301-5/1
2	1	1	BODY	1	MBsBD	Nickel Plate (납땜성 향상)	DBD01661-5/4 DBD01661-5/2
		NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2021. 05. 27.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO.,LTD. TITLE MCX50 PCB J-4R
		DRAWN BY	S.Y.EUN	
FINISH		SCALE	UNIT	A4 DWG NO. CN01095-7/2 REVISION 2 SHEET 1 of 1
		6/1	mm	